5-104068-6 - ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 5-104068-6 PCB Mount Header, Vertical, Board-to-Board, 60 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 60

Number of Rows: 2

Features



Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
PCB Mount Orientation Number of Positions	Vertical 60
Number of Positions	60
Number of Positions Number of Rows	60 2
Number of Positions Number of Rows Board-to-Board Configuration	60 2

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Operating Voltage	30 VAC
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Round Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP
Dimensions	

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2.54 mm[.1 in]
1.57 mm[.062 in]
High
-65 – 105 °C[-85 – 221 °F]
Board Standoff
Signal
Recognized
Recognized CSA, UL
CSA, UL
CSA, UL CSA LR7189, UL E28476
CSA, UL CSA LR7189, UL E28476

Other

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





TE Part # 5-147378-6 60 SYS50 SMT RCP DR SHD SN

Also in the Series | AMPMODU System 50



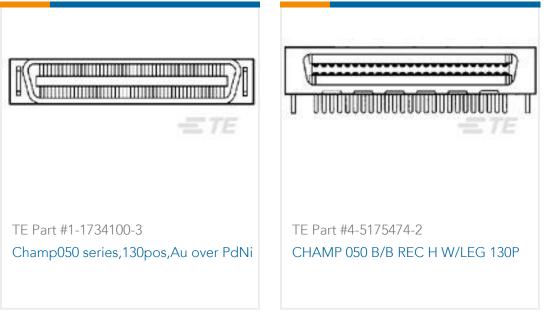
PCB Headers & Receptacles(1012)

Customers Also Bought

PCB Mount Header, Vertical, Board-to-Board, 60 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50







Documents

Product Drawings 60 SYSTEM 50 HDR DRST SHRD

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_5-104068-6_S.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-104068-6_S.3d_igs.zip

English

Customer View Model

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ENG_CVM_CVM_5-104068-6_S.3d_stp.zip
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English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Ribbon Cable Interconnect Solutions

English

Product Specifications

Application Specification

English

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Product Environmental Compliance MD_5-104068-6_07182018147_dmtec

English

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English